

REMARKS

Claims 1-50 were rejected under 35 U.S.C 102(e) over U.S. patent no. 6,787,415 to Chung et al.

1. Claim 1 recites a pedestal which “physically contacts two of the conductive lines ... insulated from each other” (last paragraph).

Claim 1 is supported by the applicants’ Figs. 2B, 2C, 2E. Each of these figures shows a pedestal 340 physically contacting two wordlines 160, which can be insulated from each other. (The claims are not limited to the embodiments discussed herein.)

The examiner associates the applicants’ pedestal with Chung’s pedestal 340 of Fig. 3B, and the applicants’ conductive lines with Chung’s wordlines 160 (Office Action, page 2, last paragraph, and page 4, line 17). Yet in Chung’s Fig. 3B, each pedestal 340 physically contacts only one wordline 160, not two wordlines as recited in Claim 1.

Claims 2-21 depend from Claim 1.

2. Claim 22 is supported by the specification and drawings as follows:

wherein the processing of the first layer (160) comprises a first etch of the first layer to form the sidewall spacers (Figs. 5A, 6A) ...;

wherein the first layer (160) as initially formed comprises a portion P1 (160E in Fig. 7A; specification, page 10, lines 2-3) going around at least said one pedestal (340), said portion P1 extending between future positions of the two conductive lines (160) which are to physically contact the pedestal (see the discussion of Claim 1 above); and

said processing of the first layer further comprises removing said portion P1 to insulate the two conductive lines from each other (specification, page 10, lines 6-9, 19-20; page 11, lines 1-2 and 15-17).

Claim 22 is believed to be allowable for any of the following two reasons. First, Claim 22 recites “two conductive lines which are to physically contact the pedestal”, and also recites removing a portion P1 “to insulate the two conductive lines from each other”. See the discussion above in connection with Claim 1.

Secondly, Claim 22 recites two etches of the first layer: a spacer forming etch and a separate etch needed to insulate the conductive lines from each other. Chung discloses a spacer forming etch of his layer 160 in Figs. 5, 6 and column 5, lines 21-26. Chung also discloses a second etch (to remove unwanted spacers) in Figs. 6-7 and column 5, lines 26-29. However, Chung does not teach that the second etch is needed to "insulate" the word lines 160 from each other as recited in Claim 22. In fact, in Chung's Fig. 6, the individual wordlines 160 are shown spaced from each other even before this second etch.

Claims 23-41 depend from Claim 22.

3. Claim 42 is believed to be allowable for reasons similar to the reasons given above for Claim 1 (note the last paragraph of Claim 42).

Claims 43-50 depend from Claim 42.

Any questions regarding this case can be addressed to the undersigned at the telephone number below.

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